

10/774,956

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	6199	(iron ferrous ferro\$8) and inductor and @ad<"19991123"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 12:07
L2	2208	L1 and (semiconductor ic (integrated adj circuit) die dice chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 12:07
L3	1102	L2 and (dielectric metallization interconnect\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 12:08
S1	38	((("3881244") or ("5095357") or ("5446311") or ("5635892") or ("5753391") or ("5801100") or ("5877533") or ("5952704") or ("6037649") or ("6040226") or ("6114937") or ("6201287") or ("5240621") or ("6281560") or ("6291305") or ("6344125")).PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/05 11:36
S2	3901	((438/622) or (257/700)).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/05 11:37
S3	2395	S2 and @ad<"19991123"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/05 16:06
S4	52	S3 and inductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/05 11:37
S5	3901	((438/622) or (257/700)).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/05 16:06
S6	2395	S5 and @ad<"19991123"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/05 16:06

S7	111	S6 and (magnetic iron ferrous)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/05 17:39
S8	19351	(magnetic iron ferrous) and inductor and @ad<"19991123"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/05 17:51
S9	6862	S8 and (semiconductor ic (integrated adj circuit) die dice chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/05 17:52
S10	9	S9 and (ild (multiple adj level adj metallization))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/05 17:42
S11	6199	(iron ferrous ferro\$8) and inductor and @ad<"19991123"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/05 17:51
S12	2208	S11 and (semiconductor ic (integrated adj circuit) die dice chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/05 17:52
S13	1102	S12 and (dielectric metallization interconnect\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 12:07